

## IEEE EPS Student Branch Chapter of University Politehnica of Bucharest

2019 can be seen as a continuation of 2018 - a new opportunity to promote the vision of SBC which represents a close collaboration between professors, professionals and students alike to different important events with the aim of driving the future of technology by improving the quality of education. Among the ones attended by our members are PCNS, EMPC and SIITME and are described, in detail, below.

Passive Components Networking Symposium (PCNS) is a bi-annual international symposium organized by the European Passive Components Institute (EPCI) in co-operation with the Faculty of Electronics, Telecommunication and Information Technology within University Politehnica of Bucharest, from 10<sup>th</sup> – 13<sup>th</sup> September in Bucharest, Romania. In its second edition, the principal ideas covered by this two-day event are related to design, materials developments, technology, reliability and application of passive electronic components for use in wide range of applications.

The event was a great success gathering a total of 61 participants out of which two members of Student Branch Chapter (SBC) were present and promoted our activity and upcoming events: 25th International Symposium for Design and Technology in Electronic Packaging (SIITME) in Cluj-Napoca from 23<sup>th</sup> – 26<sup>th</sup> October 2019 and The Interconnection Techniques In Electronics (TIE) which it is a student professional contest whose objective is to promote technological computer aided design (CAE-CAD-CAM) of electronic modules which will be taking place in Bucharest.



Valentina Dumitrașcu – Chair of IEEE-EPS Student Branch Chapter of University Politehnica of Bucharest presenting our activities at PCNS

The IEEE 22<sup>nd</sup> Microelectronics and Packaging Conference (EMPC) & Exhibition is an annual international conference which was held in Pisa, Italy from 16<sup>th</sup> – 19<sup>th</sup> September 2019 and it was organized by International Microelectronics and Packaging Society (IMAPS) and co-organized by IEEE-EPS.

EMPC 2019 offered, within the four-day program, the best of microelectronics packaging and interconnection technologies; thus, it is an established international forum dedicated to engineers working in the field and not only, gathering a total of 200 participants.

Two members of Student Branch Chapter (SBC) were there and they talked about our activities and upcoming events - 25th International Symposium for Design and Technology in Electronic Packaging (SIITME) in Cluj-Napoca from 23<sup>th</sup> – 26<sup>th</sup> October 2019 and The Interconnection Techniques In Electronics (TIE) with Prof. Christopher J. Bailey, President Elect IEEE-Electronics Packaging Society.



Prof. Christopher J. Bailey, President Elect IEEE-Electronics Packaging Society,  
 Prof. dr. eng. Paul Svasta, Valentina Dumitrașcu - Chair IEEE-EPS Student Branch Chapter of University  
 Politehnica of Bucharest

The 2019 IEEE 25th International Symposium for Design and Technology in Electronic Packaging (SIITME) is an annual international conference which was held in Cluj-Napoca, Romania from 23<sup>th</sup> – 26<sup>th</sup> October 2019. The three-day event was a successful combination between oral and poster sessions where a great number of interesting papers were presented by researchers from Romania and not only. Also, it was organized an industry session and an exhibition that informs and helps students, researchers to find joint points for possible future collaborations. This event gathered around 160 people that besides discussing about the technological aspect, it is a good chance to socialize and make new friends.

Five members of our Student Branch Chapter (SBC) participated with a booth, they could talk about our activities and future plans with Toni Mattila, Ph.D. (Tech), Adj. Prof., Regional Director (Region 8, EMEA) and other participants in the conference. Our Vice-Chair took part in the Human Resources Workshop “Strategic Partnership for Education”. All members were present at the meeting of IEEE-EPS Hu & Ro Joint Chapter.



Five members of IEEE-EPS Student Branch Chapter of University Politehnica of Bucharest at our Booth, SIITME 2019:  
 Madalin Moise, Valentina Dumitrascu, Alina Marcu, Cristina Lepadatu, Alin Serban

2019 was a great year for our SBC in which we attended to a lot of events where we successfully promoted our activity. Therefore, in a new formation, for the following year we want to increase the number of events where we can participate, we will actively be involved in the organization of TIE 2020 contest which will take place in Bucharest. Also, we want to organize a workshop dedicated to young students where new technologies that are available on the market are presented to them and help them discover what they like and follow a carrier with a job that they like.

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